

SIMPLE SWITCHER® Design Guide

national.com/switcher

Accelerate your design time with circuit and PCB design tips and recommendations.

SIMPLE SWITCHER
Easy-to-use tools. Simple solutions.

 *National*
Semiconductor

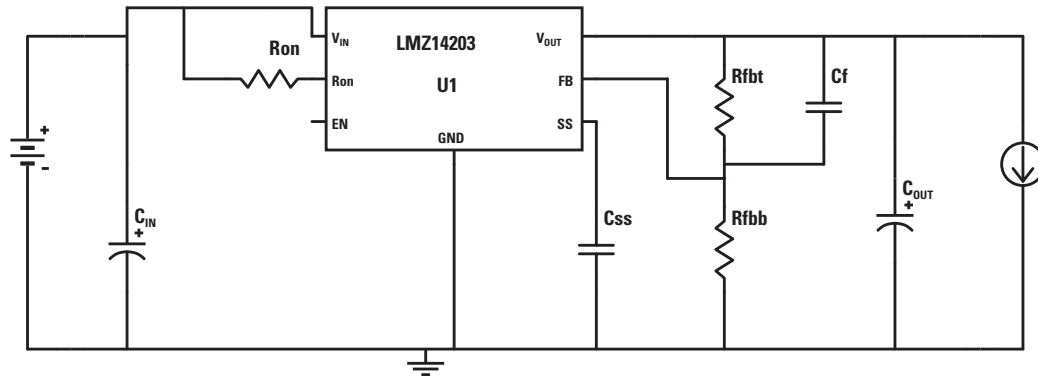
1. Introduction	
2. Power Module Designs	
LMZ1420x POL (Point Of Load) Designs (6 to 42 V_{IN} , up to 6 V_{OUT} , up to 3A).....	4
LMZ14203 Inverting Design (11 to 37 V_{IN} , as low as -5 V_{OUT} , up to 2.5A)	6
LM1200x POL Designs (4.5 to 20 V_{IN} , up to 6 V_{OUT} , up to 3A).....	8
LMZ1420xH High Output Voltage Designs (6 to 42 V_{IN} , 5V to over 24 V_{OUT} , up to 3A).....	10
LMZ10505 POL Designs (2.97 to 5.5 V_{IN} , up to 5 V_{OUT} at 5A)	12
LMZ23603/5 POL Designs (6 to 36 V_{IN} , up to 6 V_{OUT} at up to 5A).....	14
LMZ22008/10 POL Designs (6 to 20 V_{IN} , up to 6 V_{OUT} at up to 10A).....	16
LMZ12008/10 POL Designs (6 to 20 V_{IN} , up to 6 V_{OUT} at up to 10A).....	18
3. Discrete Regulators and Controller Designs	
LM2267x/LM22680 Designs (4.5 to 42 V_{IN} , 1.5 to 30 V_{OUT} up to 5A load current).....	20
LM22670 Inverting Design (6 to 35 V_{IN} , -5 V_{OUT} , up to 1.5A).....	22
LM315x Designs (4.5 to 42 V_{IN} , 1.2 to 24 V_{OUT} up to 10A load current).....	24
LM557x/LM2557x Designs (6 to 75 V_{IN} , 1.5 to 30 V_{OUT} ; V_{OUT} up to 3A load current).....	26

This design guide covers various designs using a select set of SIMPLE SWITCHER® products. For each product, the first section contains schematic, bill of material, technical tips and links to WEBENCH® designs. The second page shows the PCB layout and component placement suggestions to ensure a robust design. For more details please refer to the device datasheets and other documentation referenced.

Two different product families are introduced: The SIMPLE SWITCHER power modules and SIMPLE SWITCHER discrete regulators and controller. The SIMPLE SWITCHER power modules offer the greatest ease of use and fastest design time while the SIMPLE SWITCHER discrete regulators and controllers offer the most design flexibility.

For more information comparing the two families consult *Power Designer 129: Comparing the Merits of Integrated Power Modules versus Discrete Regulators*.

Both families are supported by the WEBENCH design tool, which creates custom power supply designs depending on the application requirements and provides the bill of material needed to create those designs.



Design Considerations

- The bulk C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple. An optional high frequency $1\ \mu\text{F}$ ceramic cap can be placed farther away to reduce noise.
- For C_{OUT} , low ESR capacitors such as ceramics are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor. C0G, X7R or X5R dielectrics are

recommended as they are stable across a larger temperature range than others.

- The R_{ENT} & R_{ENB} circuit ensures robustness and prevents early turn on of the IC as the main supply voltage ramps up. If the supply voltage should rise and fall at the UVLO voltage then the LMZ14203's output may droop. Digital loads such as FPGAs are highly sensitive to this and a monotonic rise.
- For further details refer to the Design Documentation section.

Component Values (BOM)

The following table summarizes the values chosen for the designs listed here.

Common Components across all designs

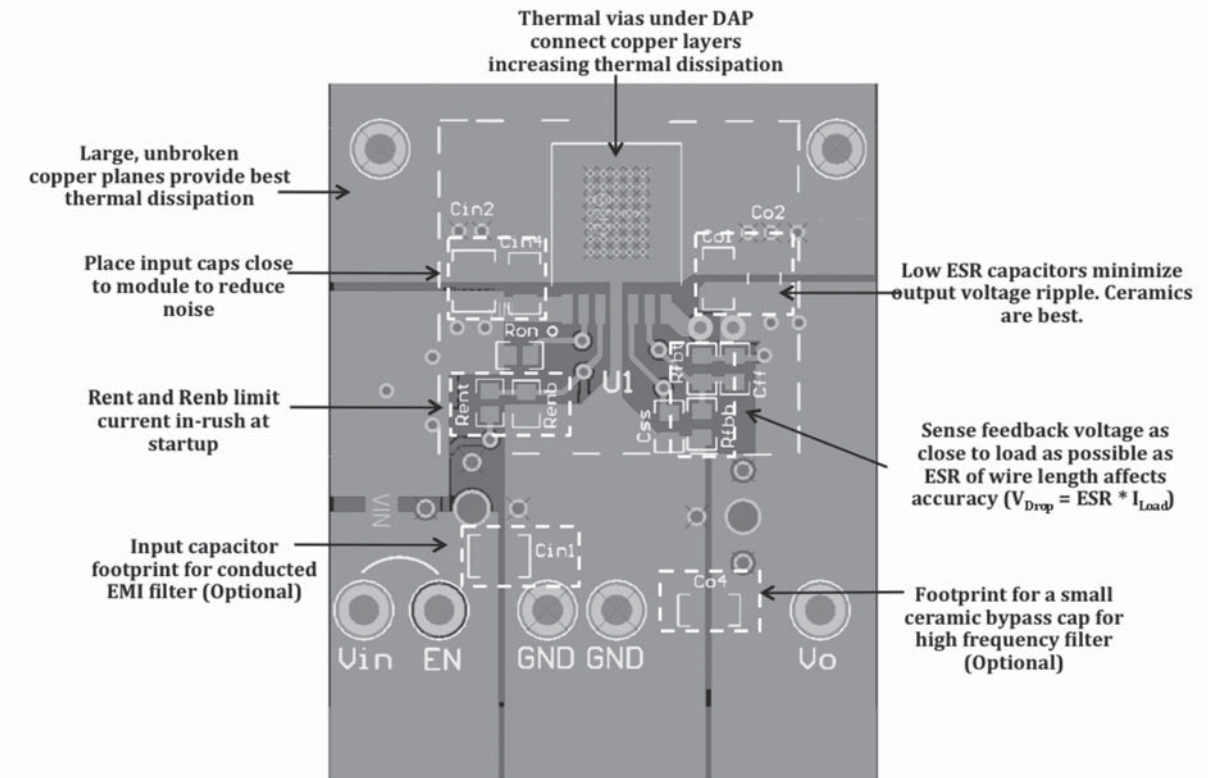
C_{IN}	C_{OUT}	C_{SS}	C_F	R_{ENT}	R_{ENB}
10 μF , X5R, 50V	100 μF , X5R, 6.3V	22 nF, X7R, 16V	22 nF, X7R 16V	68.1k Ω	11.8k Ω

Design-Specific Components

V_{IN}	V_{OUT}	R_{FBT}	R_{FBB}	R_{ON}
8 to 42V	5V	5.62 k Ω	1.07 k Ω	100 k Ω
6 to 42V	3.3V	3.32 k Ω	1.07 k Ω	61.9 k Ω
6 to 30V	2.5V	2.26 k Ω	1.07 k Ω	47.5 k Ω
6 to 25V	1.8V	1.87 k Ω	1.50 k Ω	32.4 k Ω
6 to 21V	1.5V	1.00 k Ω	1.13 k Ω	28.0 k Ω
6 to 19V	1.2V	4.22 k Ω	8.45 k Ω	22.6 k Ω
6 to 18V	0.8V	0	39.2 k Ω	24.9 k Ω

Design Documentation

- Datasheets for: LMZ14203, LMZ14202, and LMZ14201
- AN-2024: LMZ1420x / LMZ1200x Evaluation Board
- AN-2052: National Semiconductor's SIMPLE SWITCHER Power Modules and EMI



PCB effects on Thermal Performance

The SIMPLE SWITCHER power module's TO-PMOD7 package is very effective at heat transfer and PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this measures the device's temperature rise for a given power dissipation. Below are suggestions to follow when designing your PCB. For more details please refer to the datasheet and suggested further reading provided at the end.

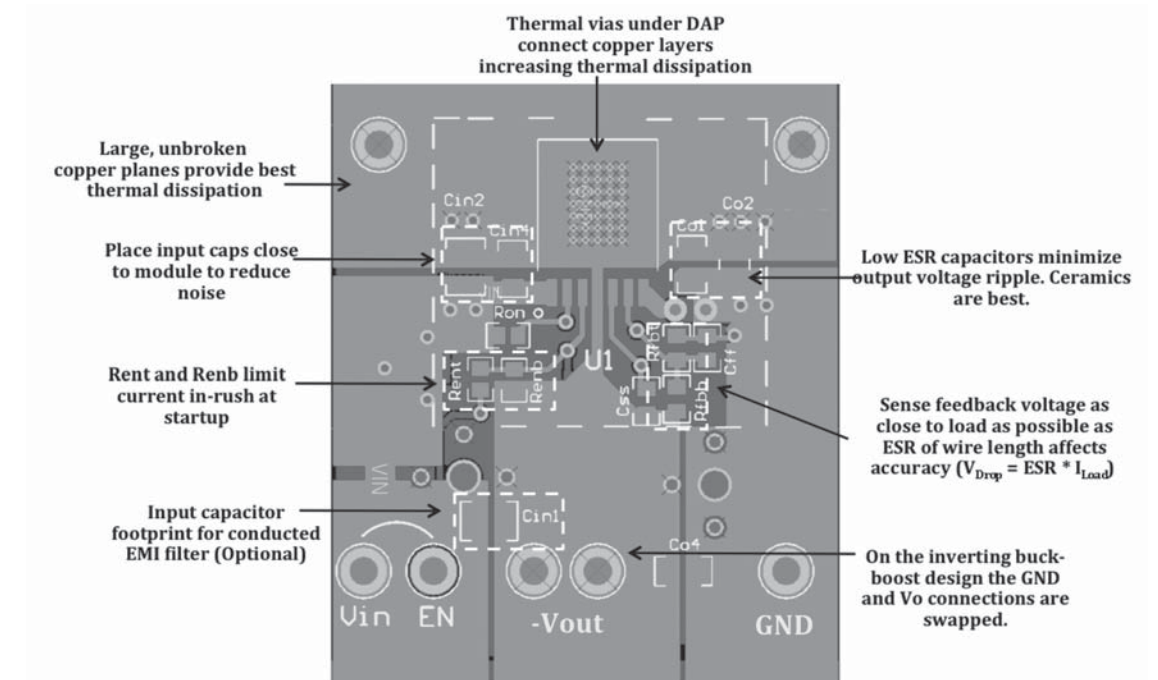
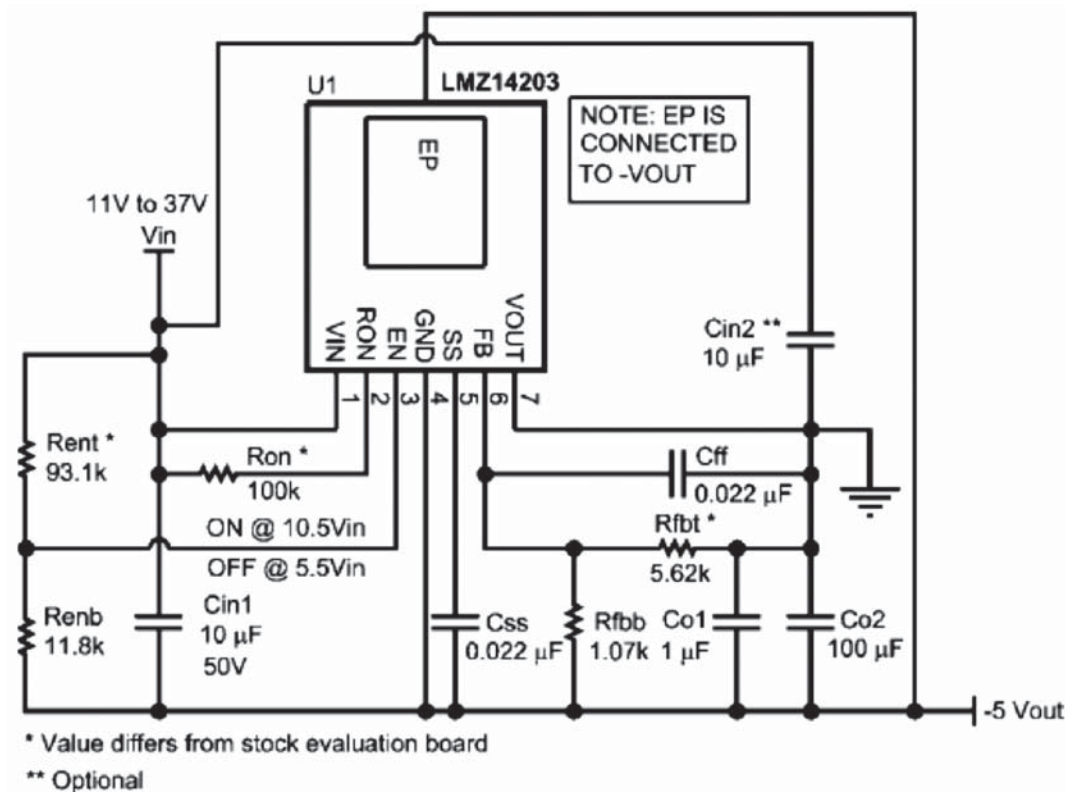
- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078; PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-2024: LMZ1420x / LMZ1200x Evaluation Board

LMZ14203 Inverting Buck-Boost Design

LMZ14203 Inverting Buck-Boost PCB Design



Design Considerations

The LMZ14203 inverting design largely follow the LMZ14203 design. As seen in the schematic, the major difference is where the ground and V_{OUT} connections are made. In addition, while the R_{ENT} & R_{ENB} circuit can still be used, hysteresis occurs which maybe undesirable.

For further details refer to the Design Documentation section.

Design Documentation

- Datasheets for: LMZ14203, LMZ14202, and LMZ14201
- AN-2027: Inverting Application for the LMZ14203 SIMPLE SWITCHER Power Module
- AN-2024: LMZ1420x / LMZ1200x Evaluation Board

Component Values (BOM)

V_{IN}	V_{OUT}	C_{IN}	C_{OUT}	C_{SS}	C_F	R_{ENT}	R_{ENB}	R_{FBT}	R_{FBB}	R_{ON}
11V to 37V	-5V	10 µF, 50V X7R	100 µF, 6.3V X5R	22nF, 16V X7R	22nF, 16V X7R	93.1 kΩ	11.8 kΩ	5.62 kΩ	1.07 kΩ	100 kΩ
11V to 37V	-3.3V	10 µF, 50V X7R	100 µF, 6.3V X5R	22nF, 16V X7R	22nF, 16V X7R	93.1 kΩ	11.8 kΩ	3.32 kΩ	1.07 kΩ	100 kΩ

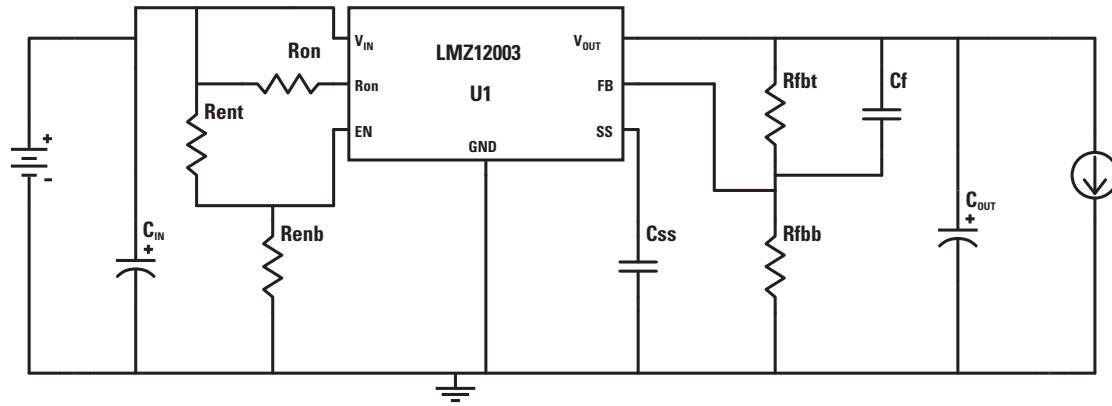
PCB effects on Thermal Performance

The SIMPLE SWITCHER Power Module's TO-PMOD7 package is very effective at heat transfer and PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this measures the device's temperature rise for a given power dissipation. Below are suggestions to follow when designing your PCB. For more details please refer to the datasheet and suggested further reading provided at the end.

- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2027: Inverting Application for the LMZ14203 SSPM
- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module



Design Considerations/Performance

- The bulk C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple. An optional high frequency 1 μ F ceramic cap can be placed farther away to reduce noise.
- For C_{OUT} , low ESR capacitors such as ceramics are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor. C0G, X7R or X5R dielectrics are recommended as they are stable across a larger temperature range than others.

- The R_{ENT} & R_{ENB} circuit ensures robustness and prevents early turn on of the IC as the main supply voltage ramps up. If the supply voltage should rise and fall at the UVLO voltage then the LMZ12003's output may droop. Digital loads such as FPGAs are highly sensitive to this and a monotonic rise.
- For further details refer to the Design Documentation section.

Design Documentation

- Datasheets for: LMZ12003, LMZ12002, and LMZ12001
- AN-2024: LMZ1420x/LMZ1200x Evaluation Board
- AN-2052: National Semiconductor's SIMPLE SWITCHER Power Modules and EMI

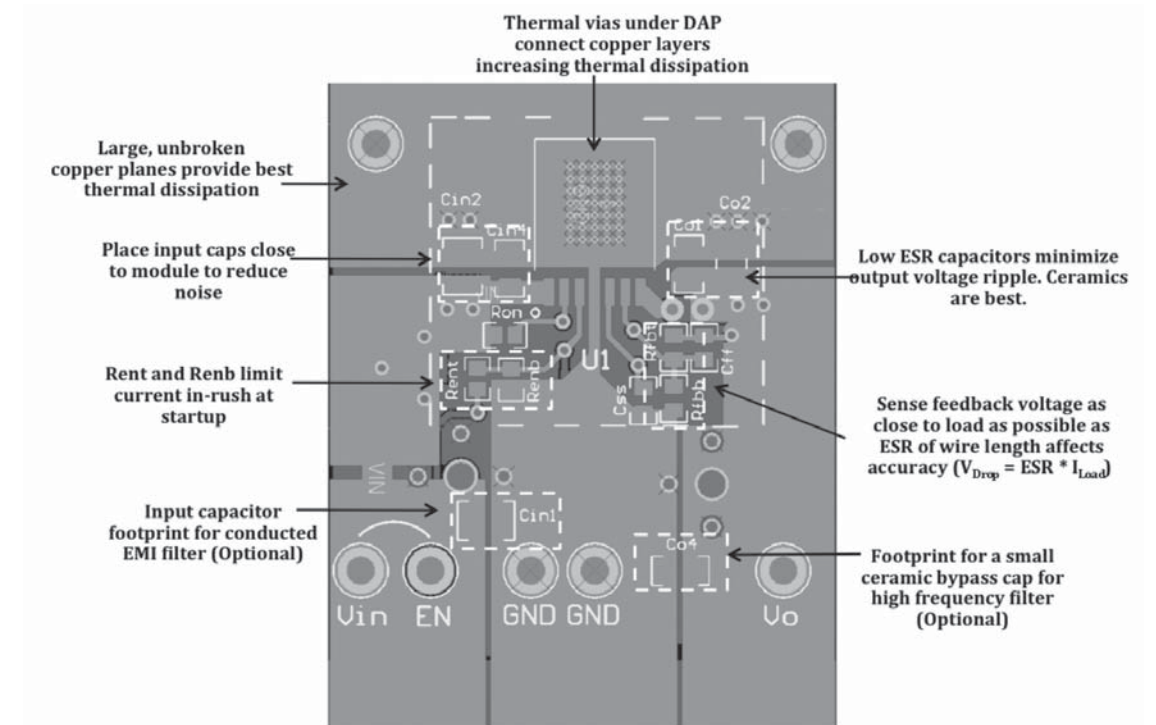
Component Values (BOM)

Common Components across all designs

C_{IN}	C_{OUT}	C_{SS}	C_F	R_{ENT}	R_{ENB}
10 μ F, X5R, 50V	100 μ F, X5R, 6.3V	22 nF, X7R, 16V	22 nF, X7R 16V	32.4 k Ω	11.8 k Ω

Design-Specific Components

V_{IN}	V_{OUT}	R_{FBT}	R_{FBB}	R_{ON}
8 to 20V	5V	5.62 k Ω	1.07 k Ω	100 k Ω
6 to 20V	3.3V	3.32 k Ω	1.07 k Ω	61.9 k Ω
5.5 to 20V	2.5V	2.26 k Ω	1.07 k Ω	47.5 k Ω
4.5 to 20V	1.8V	1.87 k Ω	1.50 k Ω	32.4 k Ω
4.5 to 20V	1.5V	1.00 k Ω	1.13 k Ω	28.0 k Ω
4.5 to 19V	1.2V	4.22 k Ω	8.45 k Ω	22.6 k Ω
4.5 to 18V	0.8V	0	39.2 k Ω	24.9 k Ω



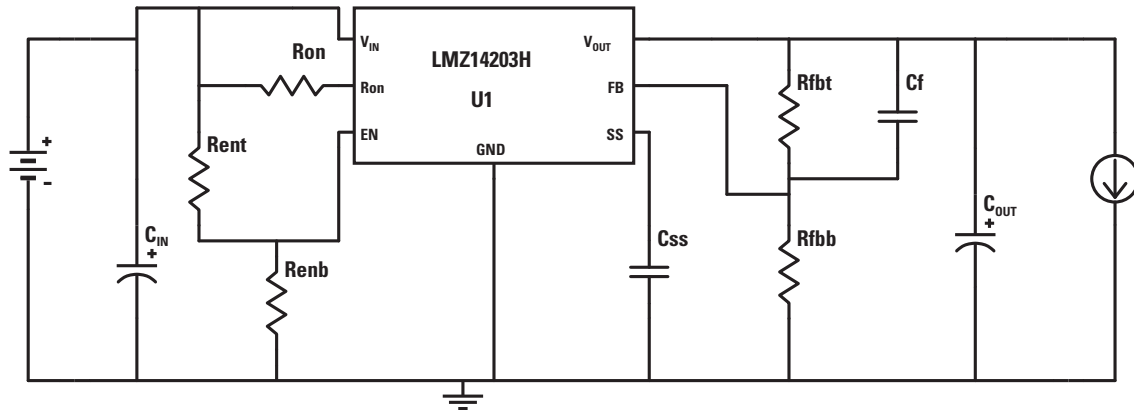
PCB effects on Thermal Performance

The TO-PMOD-7 package of the SIMPLE SWITCHER Power Module is so effective at heat transfer PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this number measures the temperature rise of the device gets for a given power dissipation. Below are guidelines when designing your PCB. For more details please refer to the datasheet and other references provided at the end.

- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-2024: LMZ1420x / LMZ1200x Evaluation Board



Design Considerations/Performance

- The bulk C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple. An optional high frequency 1 μ F ceramic cap can be placed farther away to reduce noise.
- For C_{OUT} , low ESR capacitors such as ceramics are recommended. However, ceramics have a limited voltage range and often a polymer electrolytic must be used instead. Be aware that using high ESR caps may inadvertently trigger OVP.

- The R_{ENT} & R_{ENB} circuit ensures robustness and prevents early turn on of the IC as the main supply voltage ramps up. If the supply voltage should rise and fall at the UVLO voltage then the LMZ14203H's output may droop. Digital loads such as FPGAs are highly sensitive to this and a monotonic rise.
- For further details refer to the Design Documentation section

Design Documentation

- Datasheets for: LMZ14203H, LMZ14202H, and LMZ14201H
- AN-2089: LMZ1420xH Evaluation Board
- AN-2052: National Semiconductor's SIMPLE SWITCHER Power Modules and EMI

Component Values (BOM)

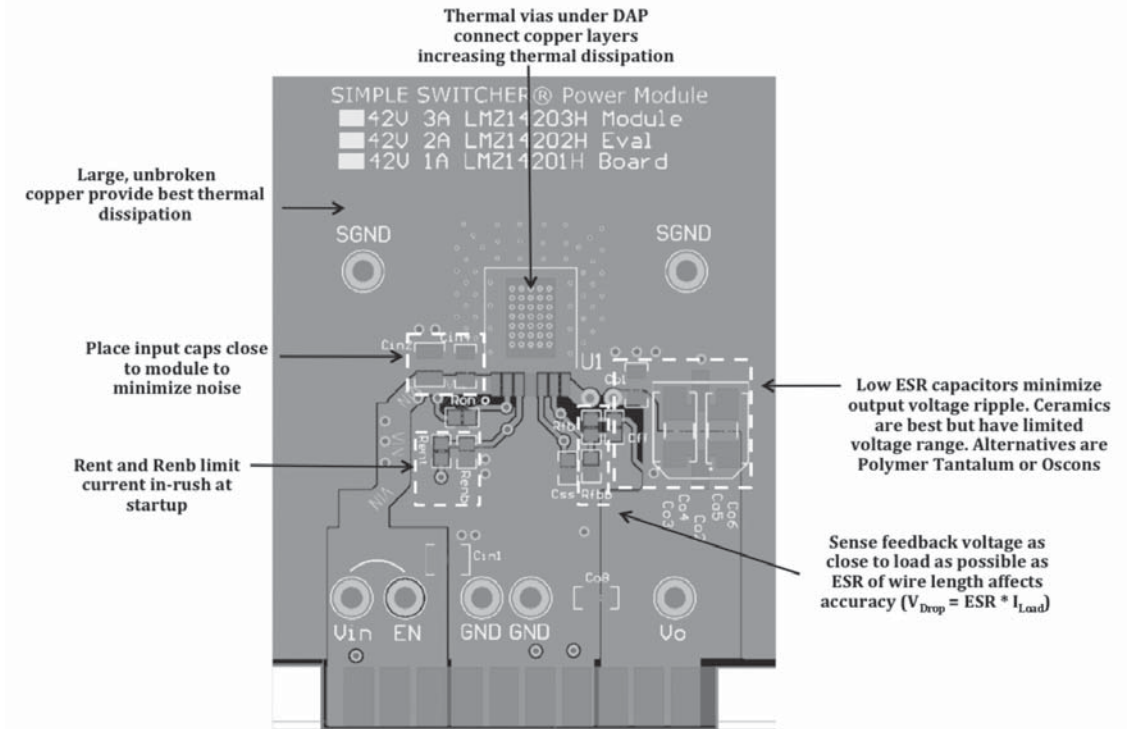
The following table summarizes the values chosen for the designs listed here.

Common Components across all designs

C_{IN}	C_{SS}	C_F	R_{ENT}	R_{FBT}	R_{ENB}
4.7 μ F, 100V, X7R	10 nF, 25V, X7R	22 nF, 50V, X7R	68.1 k Ω	34 k Ω	11.8 k Ω

Design-Specific Components

V_{IN}	V_{OUT}	C_{OUT}	R_{ENB}	R_{FBB}	R_{ON}
8 to 42V	5	100 μ F, 6.3V, X5R	11.8 k Ω	6.49 k Ω	97.6 k Ω
18 to 42V	12	47 μ F, 35V, X5R	4.75 k Ω	2.43 k Ω	187 k Ω
18 to 42V	15	33 μ F, 35V, Tantalum	4.75 k Ω	1.91 k Ω	357 k Ω
24 to 42V	18	33 μ F, 35V, Tantalum	3.57 k Ω	1.58 k Ω	287 k Ω
30 to 42V	24	47 μ F, 35V, AL Polymer	2.8 k Ω	1.18 k Ω	487 k Ω



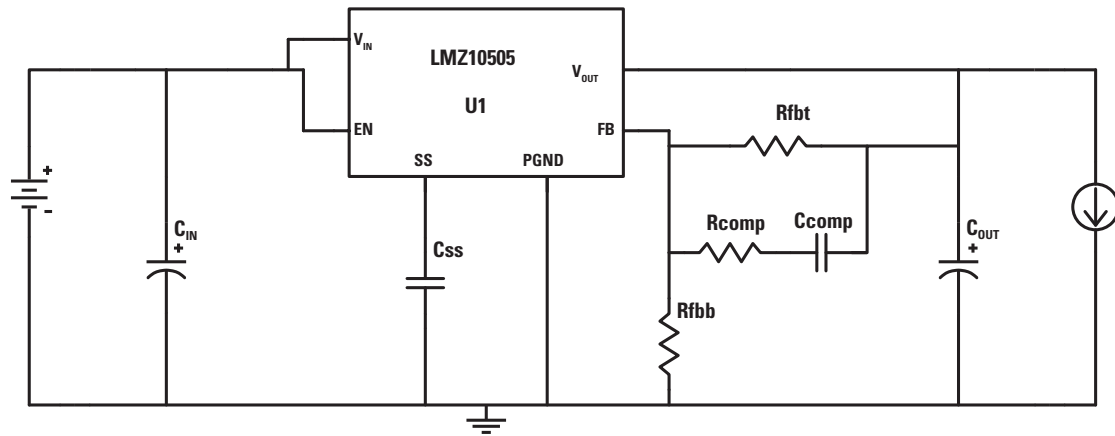
PCB effects on Thermal Performance

The TO-PMOD7 package of the SIMPLE SWITCHER power module is so effective at heat transfer PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this number measures the temperature rise of the device gets for a given power dissipation. Below are guidelines when designing your PCB. For more details please refer to the datasheet and other references provided at the end.

- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-2024: LMZ1420x / LMZ1200x Evaluation Board



Design Considerations/Performance

- The bulk C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple.
- For C_{OUT} , low ESR capacitors such as ceramics are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor. C0G, X7R or X5R dielectrics are recommended as they are stable across a larger temperature range than others.

- The LMZ10505 features an internal Type II compensation network. To optimize load transient performance, add a resistor and capacitor (Type III compensation) network across the upper feedback resistor. Choosing these components changes the crossover frequency of the converter and affects responsiveness to load transients. These components also affect phase margin which is a measure of the stability of the power supply to load transients.
- For further details refer to the Design Documentation section

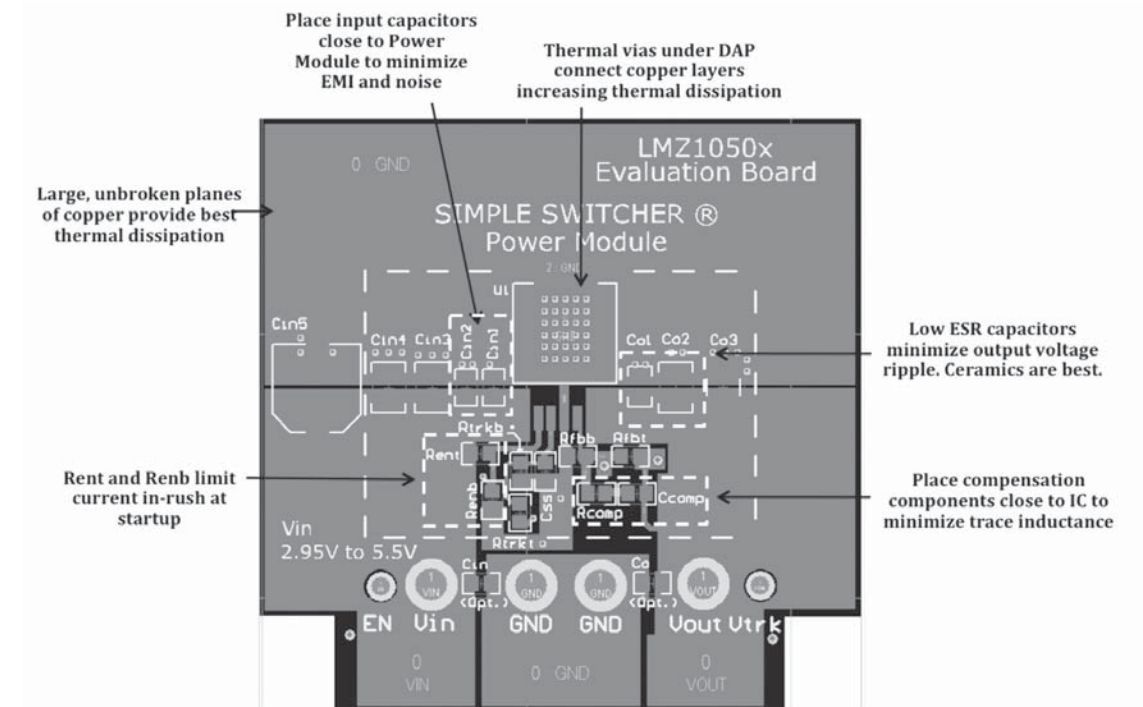
Design Documentation

- Datasheets: LMZ10505, LMZ10504, LMZ10503
- AN-2013: LMZ1050x SIMPLE SWITCHER Power Module Quick Compensation Guide

Component Values (BOM)

The following table summarizes the values chosen for the designs listed here.

V_{IN}	V_{OUT}	I_{OUT}	C_{IN}	C_{OUT}	C_{SS}	C_{COMP}	R_{COMP}	R_{FBT}	R_{FBB}
5v	0.9	5A	10 μ F, 10V X5R	100 μ F, 6.3V X5R	2.7 nF, 50V X7R	390 pF, 50V X7R	511 Ω	43.2 k Ω	340 k Ω
5V	1.2	5A	10 μ F, 10V X5R	100 μ F, 6.3V X5R	2.7 nF, 50V X7R	390 pF, 50V X7R	511 Ω	43.2 k Ω	86.6 k Ω
5V	1.5	5A	10 μ F, 10V X5R	100 μ F, 6.3V X5R	2.7 nF, 50V X7R	220 pF, 50V X7R	909 Ω	61.9 k Ω	54.9 k Ω
5V	1.8	5A	4.7 μ F, 50V X5R	47 μ F, 6.3V X5R	2.7 nF, 50V X7R	180 pF, 50V X7R	523 Ω	52.3 k Ω	64.9 k Ω
5V	2.5	5A	4.7 μ F, 50V X5R	47 μ F, 6.3V X5R	2.7 nF, 50V X7R	100 pF, 50V X7R	931 Ω	82.5 k Ω	39.2 k Ω
5V	3.3	5A	4.7 μ F, 50V X5R	47 μ F, 16V X5R	2.7 nF, 50V X7R	100 pF, 50V X7R	931 Ω	82.5 k Ω	26.7 k Ω



PCB effects on Thermal Performance

The TO-PMOD7 package of the SIMPLE SWITCHER power module is so effective at heat transfer PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this number measures the temperature rise of the device gets for a given power dissipation. Below are guidelines when designing your PCB. For more details please refer to the datasheet and other references provided at the end.

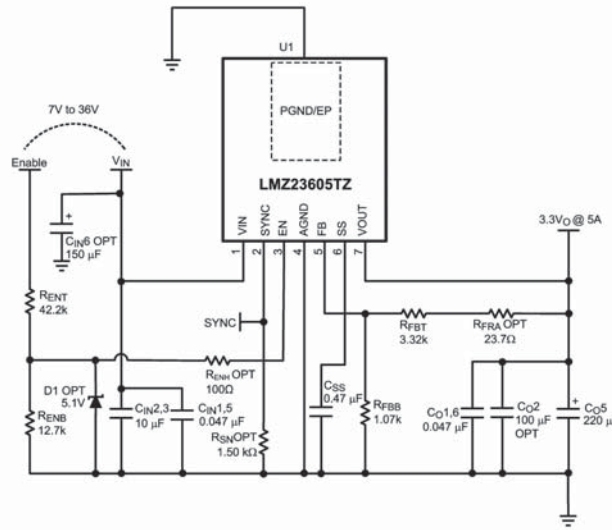
- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-2022: LMZ1050x Evaluation Board

Design Considerations

- The C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple. An optional high frequency 1 μ F ceramic cap can be placed farther away to reduce noise.
- For C_{OUT} , low ESR capacitors such as ceramics are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor. C0G, X7R or X5R dielectrics are recommended as they are stable across a larger temperature range than others.
- The R_{ENT} & R_{ENB} circuit ensures robustness and prevents early turn on of the IC as the main supply voltage ramps up. If the supply voltage should rise and fall at the UVLO voltage then the LMZ23605's output may droop. Digital loads such as FPGAs are highly sensitive to this and a monotonic rise.
- For further details refer to the Design Documentation section



Design Documentation

- Datasheets for: LMZ23605 and LMZ23603
- AN-2085: LMZ2360x / LMZ2200x Evaluation Board
- AN-2125: LMZ23605 Demonstration Board

Component Values (BOM)

Common Components across all designs

C_{IN}	C_{OUT}	C_{SS}	R_{SN}	R_{ENT}	R_{ENB}	R_{ENH}
10 μ F, X7R, 50V	100 μ F, X7R, 6.3V	0.47 μ F, X7R, 16V	1.5 k Ω	42.2 k Ω	12.7 k Ω	100 Ω

Common Components across all designs

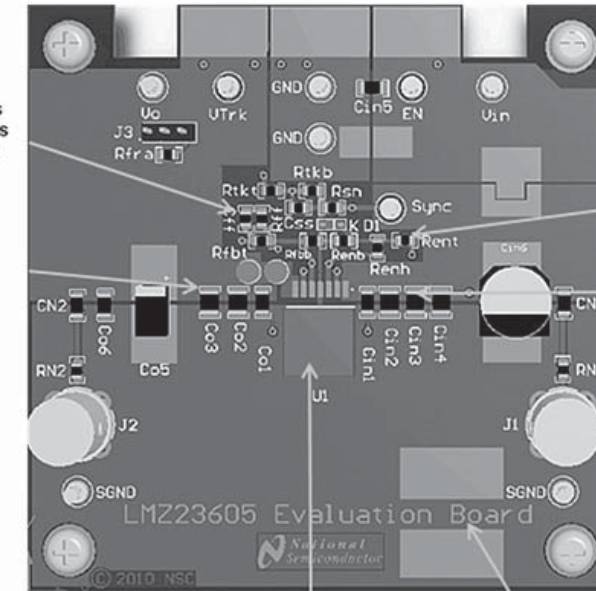
C_{IN} (opt)	C_{OUT} (opt)	R_{FRA} (opt)	D1 (opt)
150 μ F, CAP, AL, 50V	220 μ F, SP-CAP, 6.3V	23.7 Ω	0.5W, 5.1V

Design-specific components

V_{IN}	V_{OUT}	R_{FBT}	R_{FBB}
10 to 36V	6V	15.4 k Ω	2.37 k Ω
9 to 36V	5V	5.62 k Ω	1.07 k Ω
7 to 36V	3.3V	3.32 k Ω	1.07 k Ω
6 to 36V	2.5V	2.26 k Ω	1.07 k Ω
6 to 36V	1.8V	1.87 k Ω	1.5 k Ω
6 to 36V	1.5V	1.00 k Ω	1.13 k Ω
6 to 36V	1.2V	1.07 k Ω	2.05 k Ω
6 to 36V	1.0V	1.62 k Ω	6.49 k Ω
6 to 36V	0.8V	0	8.06 k Ω

Sense feedback voltage as close to load as possible as ESR of wire length affects accuracy

Low ESR caps minimize output voltage ripple. Ceramics are best.



Thermal vias under DAP connect copper layers increasing thermal dissipation

Large, unbroken copper planes provide best thermal dissipation

PCB effects on Thermal Performance

The SIMPLE SWITCHER power module's TO-PMOD7 package is very effective at heat transfer and PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this measures the device's temperature rise for a given power dissipation. Below are suggestions to follow when designing your PCB. For more details please refer to the datasheet and suggested further reading provided at the end.

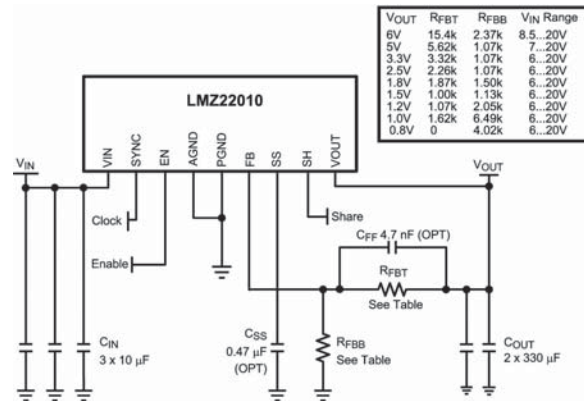
- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-2085: LMZ2360x / LMZ2200x Evaluation Board
- AN-2125: LMZ23605 Demonstration Board

Design Considerations

- The C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple. An optional high frequency $1\mu\text{F}$ ceramic cap can be placed farther away to reduce noise.
- For C_{OUT} , low ESR capacitors such as Poscap or SP caps are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor.
- The R_{ENT} & R_{ENB} circuit ensures robustness and prevents early turn on of the IC as the main supply voltage ramps up. If the supply voltage should rise and fall at the UVLO voltage then the LMZ22008/10's output may droop. Digital loads such as FPGAs are highly sensitive to this and a monotonic rise.
- For further details refer to the Design Documentation section



Design Documentation

- Datasheets for: LMZ22010 and LMZ22008
- AN-2093: LMZ236xx / LMZ20xx Evaluation Board

Component Values (BOM)

Common Components across all designs

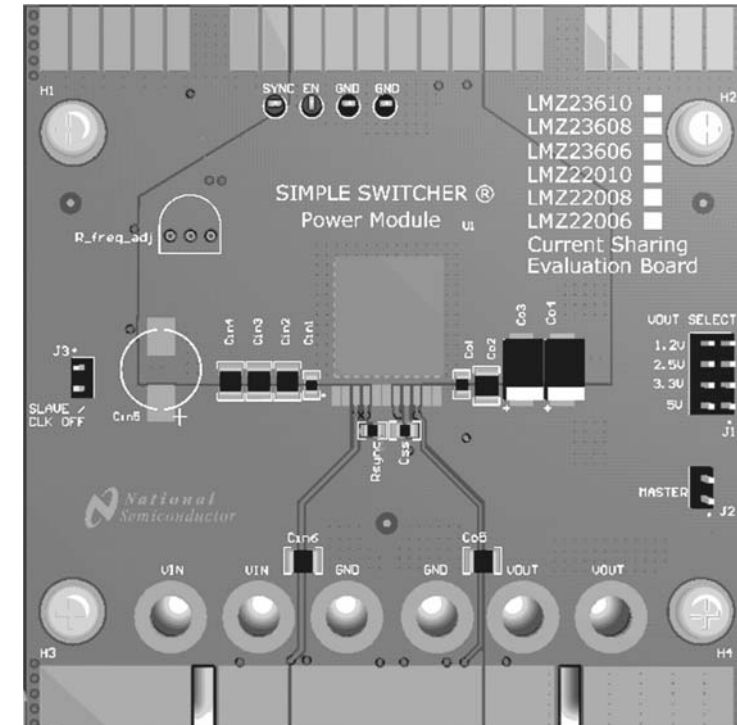
C_{IN}	C_{OUT}	C_{SS}	R_{SN}	R_{ENT}	R_{ENB}	R_{ENH}
3 x 10uF, 50V	2 x 330uF, 6.3V	0.47uF, 16V	1.5K	42.2K	12.7K	NA

Common Components across all designs

C_{IN} (opt)	C_{OUT} (opt)	D1 (opt)
150 μF , CAP, AL, 50V	2 x 47uF, 10V	5.1V, 0.5W

Design-specific components

V _{IN}	V _{OUT}	R _{FBT}	R _{FBB}
8.5 to 20V	6V	15.4 k Ω	2.37 k Ω
7 to 20V	5V	5.62 k Ω	1.07 k Ω
6 to 20V	3.3V	3.32 k Ω	1.07 k Ω
6 to 20V	2.5V	2.26 k Ω	1.07 k Ω
6 to 20V	1.8V	1.87 k Ω	1.5 k Ω
6 to 20V	1.5V	1.00 k Ω	1.13 k Ω
6 to 20V	1.2V	1.07 k Ω	2.05 k Ω
6 to 20V	1.0V	1.62 k Ω	6.49 k Ω
6 to 20V	0.8V	0	4.02 k Ω



PCB effects on Thermal Performance

The SIMPLE SWITCHER Power Module's TO-PMOD11 package is very effective at heat transfer and PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this measures the device's temperature rise for a given power dissipation. Below are suggestions to follow when designing your PCB. For more details please refer to the datasheet and suggested further reading provided at the end.

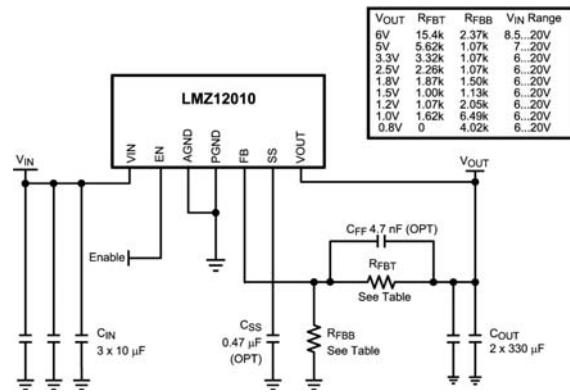
- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-2093: LMZ236xx / LMZ20xx Evaluation Board

Design Considerations

- The C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple. An optional high frequency 1 μ F ceramic cap can be placed farther away to reduce noise.
- For C_{OUT} , low ESR capacitors such as Poscap or SP caps are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor.
- The R_{ENT} & R_{ENB} circuit ensures robustness and prevents early turn on of the IC as the main supply voltage ramps up. If the supply voltage should rise and fall at the UVLO voltage then the LMZ12008/10's output may droop. Digital loads such as FPGAs are highly sensitive to this and a monotonic rise.
- For further details refer to the Design Documentation section



Design Documentation

- Datasheets for: LMZ12010 and LMZ12008
- AN-xxxx: LMZ136xx / LMZ10xx Demonstration Board

Component Values (BOM)

Common components across all designs (R_{ENT} and R_{ENB} – On EVB but not required)

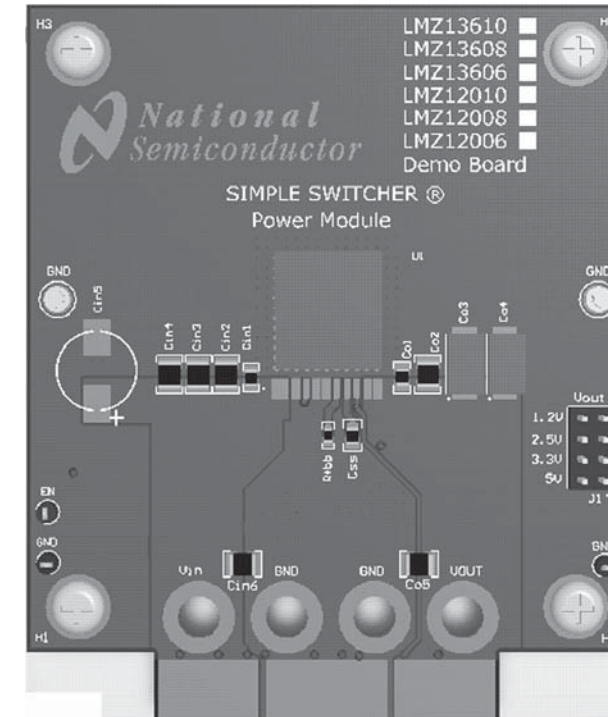
C_{IN}	C_{OUT}	C_{SS}	R_{SN}	R_{ENT}	R_{ENB}	R_{ENH}
3 x 10 μ F, 50V	2 x 330 μ F, 6.3V	0.47 μ F, 16V	1.5K	42.2K	12.7K	NA

Common Components across all designs

C_{IN} (opt)	C_{OUT} (opt)	R_{FRA} (opt)	D1 (opt)
2 x 0.047 μ F, 50V	2 x 47 μ F, 10V	NA	5.1V, 0.5W

Design specific components

V _{IN}	V _{OUT}	R _{FBT}	R _{FBB}
8.5 to 20V	6V	15.4 k Ω	2.37 k Ω
7 to 20V	5V	5.62 k Ω	1.07 k Ω
6 to 20V	3.3V	3.32 k Ω	1.07 k Ω
6 to 20V	2.5V	2.26 k Ω	1.07 k Ω
6 to 20V	1.8V	1.87 k Ω	1.5 k Ω
6 to 20V	1.5V	1.00 k Ω	1.13 k Ω
6 to 20V	1.2V	1.07 k Ω	2.05 k Ω
6 to 20V	1.0V	1.62 k Ω	6.49 k Ω
6 to 20V	0.8V	0	4.02 k Ω



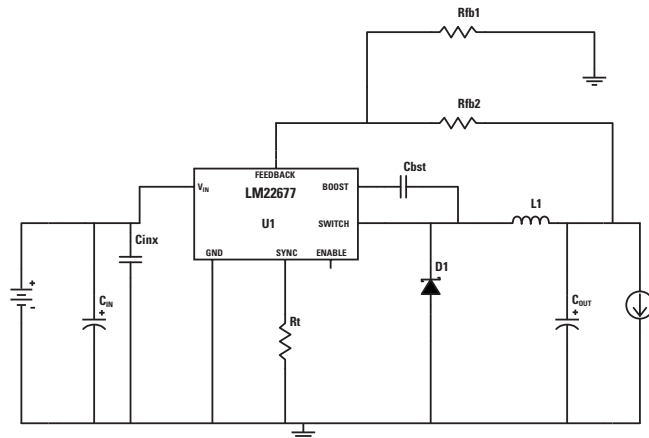
PCB effects on Thermal Performance

The SIMPLE SWITCHER power module's TO-PMOD11 package is very effective at heat transfer and PCB design has a great impact on the overall thermal performance of the device. Commonly referred to as θ_{JA} , this measures the device's temperature rise for a given power dissipation. Below are suggestions to follow when designing your PCB. For more details please refer to the datasheet and suggested further reading provided at the end.

- Solder the package's exposed pad DAP to ground plane
- Use copper planes with a 2-ounce copper weight
- Connect the copper planes with thermal vias
- Larger unbroken PCB area provide better thermal dissipation

Suggested Further Reading

- AN-2026: The effect of PCB Design on the Thermal Performance of SIMPLE SWITCHER Power Module
- AN-2020: Thermal Design by Insight, Not Hindsight
- AN-2078: PCB Layout For National Semiconductor's SIMPLE SWITCHER Power Module
- AN-xxxx: LMZ136xx / LMZ10xx Demonstration Board



Design Considerations/Performance

- The bulk C_{IN} input capacitor supplies the instantaneous current demands of the IC and must be sized to satisfy the input ripple current requirement. Low ESR or ceramic capacitors are suggested to minimize input voltage ripple.
- For C_{OUT} , low ESR capacitors such as ceramics are recommended. This reduces output ripple but make sure to account for a DC bias derating when sizing the capacitor. C0G, X7R or X5R dielectrics are recommended as they are stable across a larger temperature range than others. Higher value capacitors can be placed in parallel to provide bulk capacitance during transient load steps.

- The re-circulating diode, D1, should be a Schottky due to its reverse recovery characteristics and low forward voltage drop. This helps improve efficiency of the converter.
- The schematic and PCB layout shown are for the LM22677 but apply to all LM2267x/LM22680 devices. For BOM component choice using devices other than LM22677 please use the WEBENCH links below to run the designs.
- For further details refer to the Design Documentation section

Design Documentation

- Datasheets: LM22670, LM22671, LM22672, LM22673, LM22674, LM22675, LM22676, LM22677, LM22678, LM22679, LM22680
- AN2024: LMZ1420x/LMZ1200x Evaluation Board
- AN-1246: Stresses in Wide Input DC-DC Converters

Component Values (BOM)

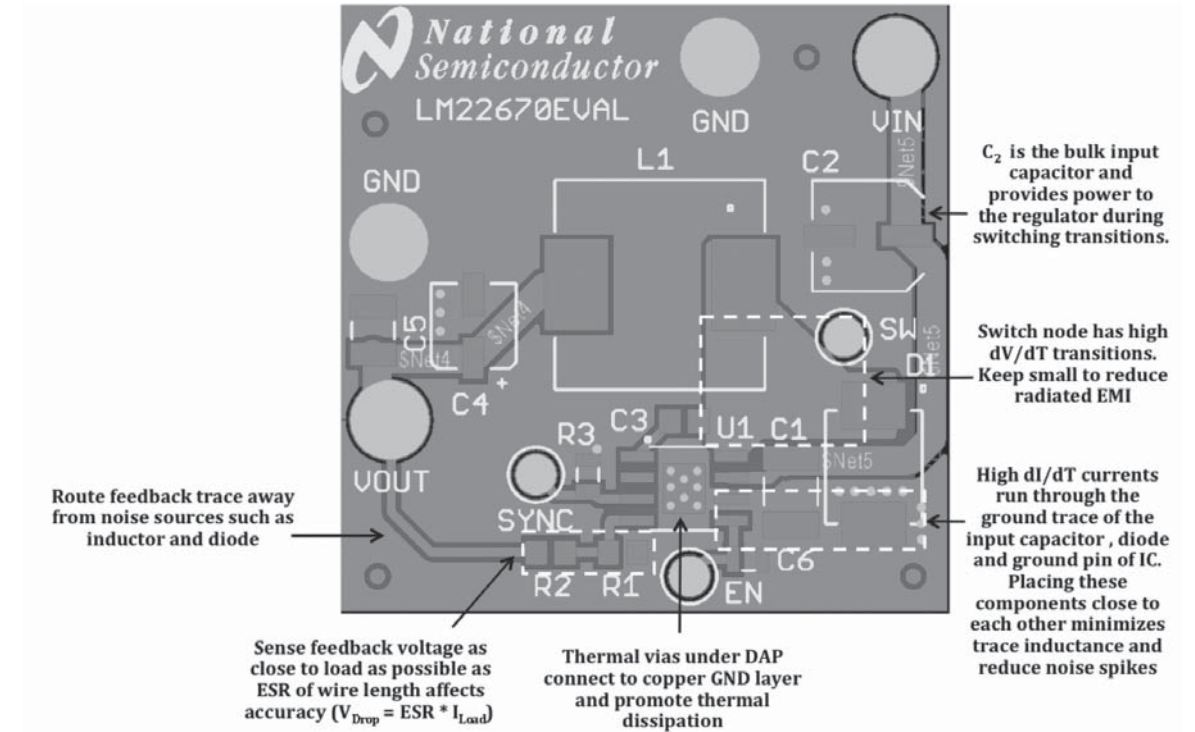
The following table summarizes the values chosen for the designs listed here.

Common Components across all designs

C_{BST}	C_{INX}	D1
10 nF, 50V, X7R	1 μ F, 100V, X7R	100V, Schottky Diode

Design-Specific Components

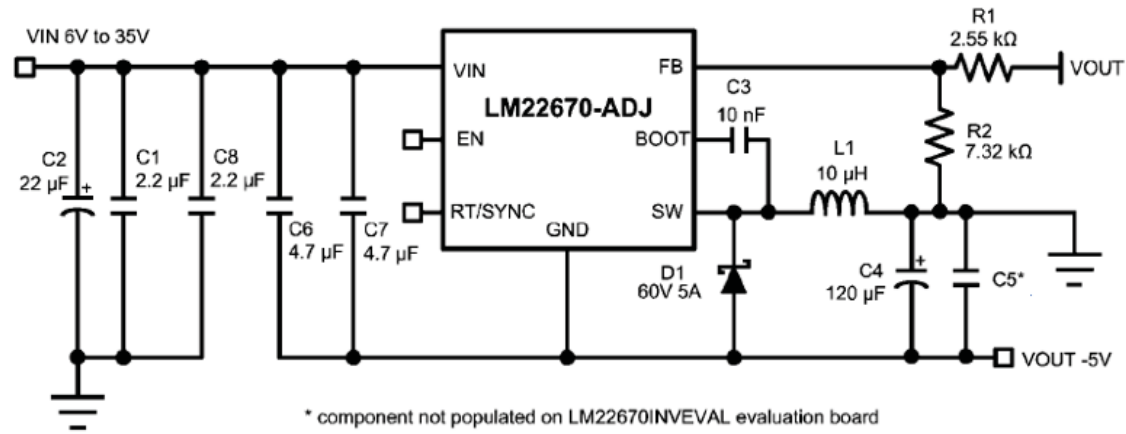
V_{IN}	V_{OUT}	C_{IN}	C_{OUT}	L1	R_{FB1}	R_{FB2}	R_L
4.5 to 42	1.5	150 μ F, 200V AL-EI	680 μ F, 2.5V AL Polymer	4.7 μ H	1 k Ω	169 Ω	113 k Ω
4.5 to 42	1.8	150 μ F, 200V AL-EI	680 μ F, 2.5V AL Polymer	4.7 μ H	1 k Ω	402 Ω	102 k Ω
4.5 to 42	2.5	150 μ F, 200V AL-EI	470 μ F, 4V AL Polymer	4.7 μ H	1 k Ω	953 Ω	82.5 k Ω
4.5 to 42	3.3	68 μ F, 200V AL-EI	180 μ F, 6.3V AL Polymer	10 μ H	1 k Ω	1.58 k Ω	182 k Ω
7 to 42	5	150 μ F, 200V AL-EI	68 μ F, 10V AL Polymer	10 μ H	1 k Ω	2.87 k Ω	100 k Ω
18 to 42	12	100 μ F, 250V AL-EI	33 μ F, 16V AL-EI	18 μ H	1 k Ω	8.45 k Ω	113 k Ω
24 to 42	15	2.2 μ F, 100V AL-EI	100 μ F, 25V AL-EI	22 μ H	1 k Ω	10.7 k Ω	118 k Ω
36 to 42	18	4.7 μ F, 100V AL-EI	22 μ F, 35V AL-EI	22 μ H	1 k Ω	13 k Ω	110 k Ω
36 to 42	24	2.2 μ F, 100V AL-EI	100 μ F, 35V AL-EI	22 μ H	1 k Ω	17.8 k Ω	165 k Ω



Suggested Further Reading

- AN-1892: LM22677 Evaluation Board
- AN-1891: LM22679 Evaluation Board
- AN-1894: LM22673 Evaluation Board
- AN-1885: LM22670 Evaluation Board
- AN-1911: LM22680 Evaluation Board
- AN-1896: LM22672 Evaluation Board
- AN-1895: LM22671 Evaluation Board
- AN-1229: SIMPLE SWITCHER PCB Layout Guidelines
- AN-1149: Layout Guidelines for Switching Power Supplies
- Online Seminar: PCB Layout for Switchers
- AN-1157: Positive to Negative Buck-Boost converter using LM267x

LM2267x/LM22680 Inverting Buck-Boost Design



Design Considerations/Performance

- The LM22680 inverting buck-boost schematic shown above is similar to the LM22680 standard buck design but with some critical differences. C6 and C7 are additional capacitors connecting the input to the negative output to provide additional phase margin for stability. The GND pin of the IC is also connected to $-V_{OUT}$ and the feedback pin's references to ground.
- The design presented here can apply to any of the LM2267x/LM22680 family.
- For further details refer to the Design Documentation section.

Design Documentation

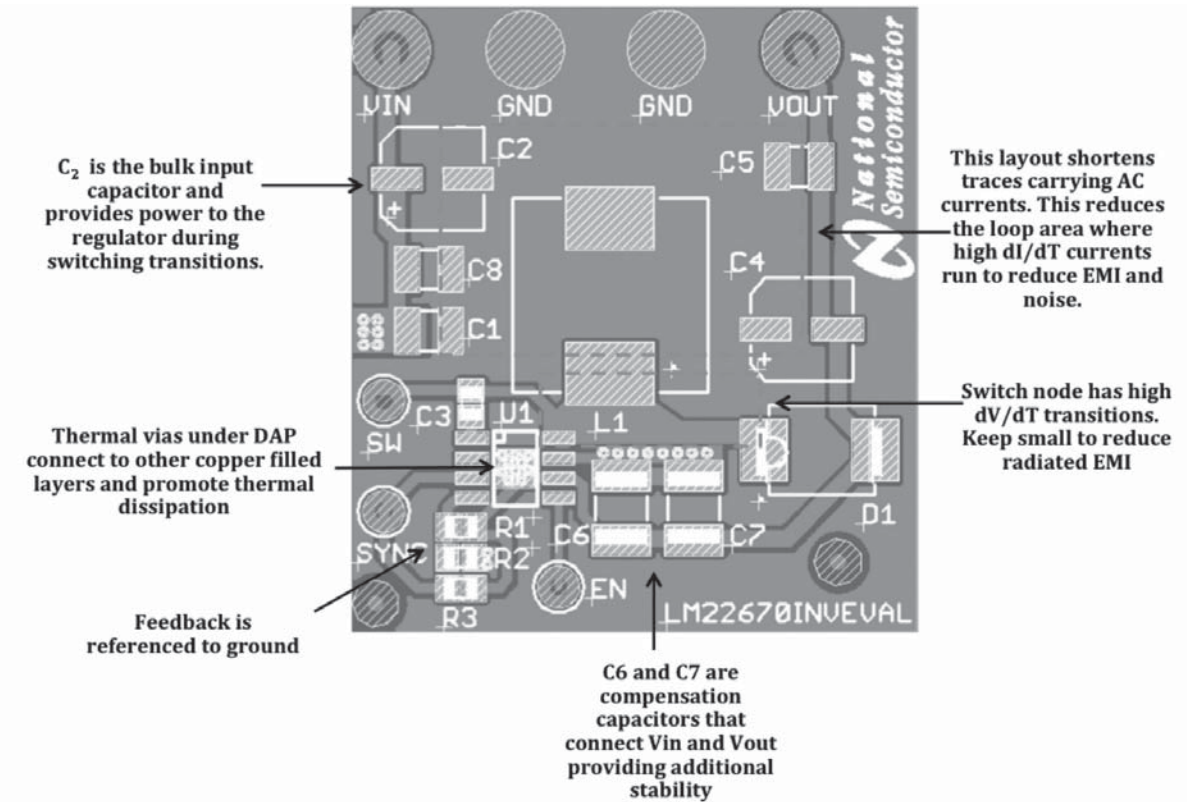
- Datasheets: LM22670, LM22671, LM22672, LM22673, LM22674, LM22675, LM22676, LM22677, LM22678, LM22679, LM22680
- AN-1888: LM22670 Evaluation Board Inverting Topology

Component Values (BOM)

The following table summarizes the values chosen for the designs listed here.

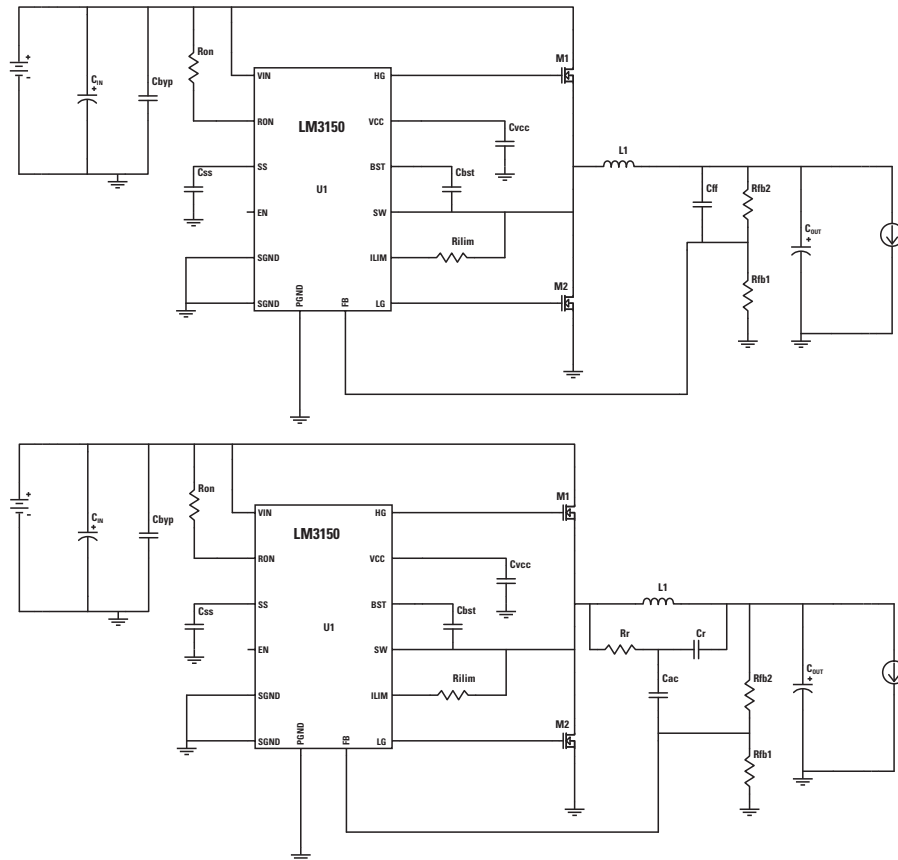
C _{IN1}	C _{IN2}	C _{IN6}	C _{IN7}	C _{IN8}	L1	C _{BOOT3}	C _{OUT4}	R1	R2
2.2 μF 50V, X7R	22 μF, 63V, AL-EI	4.7 μF, X7R, 50V	4.7 μF, 50V, X7R	2.2 μF, 50V, X7R	10 μH	10 nF 50V, X7R	120 μF AL Polymer, 6.3V	2.55 kΩ	7.32 kΩ

LM2267x/LM22680 Inverting Buck-Boost PCB Design



Suggested Further Reading

- AN-1888: LM22670 Evaluation Board Inverting Topology and Application Notes
- AN-1229: SIMPLE SWITCHER PCB Layout Guidelines
- AN-1149: Layout Guidelines for Switching Power Supplies
- Online Seminar: PCB Layout for Switchers



Use top schematic for 5V and below. Use bottom schematic for 12V and above.

Design Considerations/Performance

- Two schematics are presented depending on the desired output voltage. The schematic used when the output voltage is 12V or above uses R_r and C_r to generate the necessary ripple voltage while the C_{ac} capacitor AC couples the signal to the feedback pin for proper regulation.
- When selecting M1 and M2, choosing low $R_{ds(on)}$ FETs is necessary to minimize conduction losses. However, pay attention to the FETs' gate charge (Q_g) requirements and the switching frequency to ensure that switching losses does not result in excessive power dissipation.

- The schematic and PCB layout shown are for the LM3150 but apply to all LM315x devices. For BOM component choice using devices other than LM3150 please use the WEBENCH links below to run the designs.
- For further details refer to the Design Documentation section.

Design Documentation

- Datasheet: LM3150, LM3151, LM3152, and LM3153.
- AN1628: Minimizing FET Losses in a High Input Rail Buck Converter
- AN1628: Minimizing FET Losses in a High Input Rail Buck Converter (Chinese)
- AN1481: Controlling Output Ripple and Achieving ESR Independence in COT designs

Component Values (BOM)

The following table summarizes the values chosen for the designs listed here.

Common Components across all designs

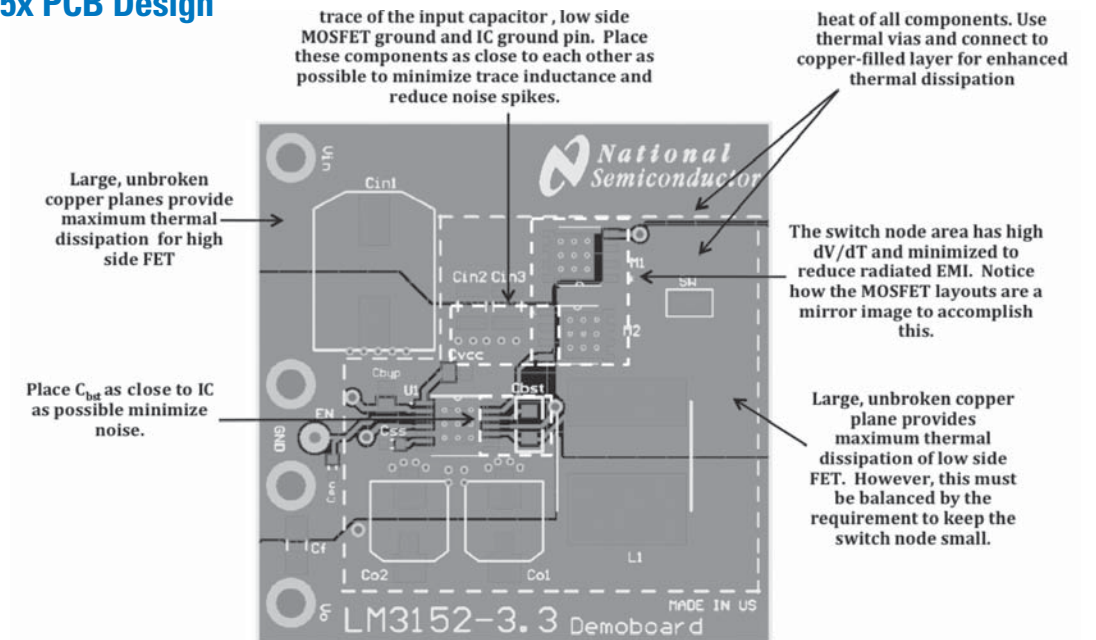
C_{BST}	C_{BYP}	C_{SS}	M1	M2
470 nF, 16V X7R	100 nF, 100V X7R	15 nF, 50V X7R	$V_{dsMax}=80V$ 100A	$V_{dsMax}=80V$ 100A

Design-Specific Components

V_{IN}	V_{OUT}	I_{OUT}	C_{FF}	C_{IN}	C_{OUT}	C_{VCC}	L1	R_{FB1}	R_{FB2}	R_{ILIM}	R_{ON}
6 to 42V	1.2V	5A	2.7 nF, 50V X7R	27.872 μ F, 56V	1 mF, 2.5V Tantalum	1 μ F, 10V X7R	6 μ H	10 k Ω	10 k Ω	2.05 k Ω	51.1 k Ω
6 to 42V	1.5V	5A	2.2 nF, 50V X7R	30.126 μ F, 56V	680 μ F, 4V Tantalum	1 μ F, 10V X7R	6 μ H	10 k Ω	15 k Ω	2.05 k Ω	59 k Ω
6 to 42V	1.8	5A	1.6 nF, 50V X7R	32.266 μ F, 56V	470 μ F, 6.3V Tantalum	1 μ F, 10V X7R	6 μ H	10 k Ω	20 k Ω	2.05 k Ω	66.5 k Ω
6 to 42V	2.5	5A	1.1 nF, 50V X7R	35.746 μ F, 56V	330 μ F, 6.3V Tantalum	1 μ F, 10V X7R	6.8 μ H	10 k Ω	31.6 k Ω	2.05 k Ω	78.7 k Ω
6 to 42V	3.3	5A	820 pF, 50V X7R	37.401 μ F, 56V	220 μ F, 6.3V Tantalum	1 μ F, 10V X7R	10 μ H	10 k Ω	45.3 k Ω	2.05 k Ω	84.5 k Ω
7 to 42	5	5A	560 pF, 50V X7R	29.742 μ F, 50V	68 μ F, 20V Tantalum	1 μ F, 10V X7R	10 μ H	10 k Ω	73.2 k Ω	2.1 k Ω	95.3 k Ω

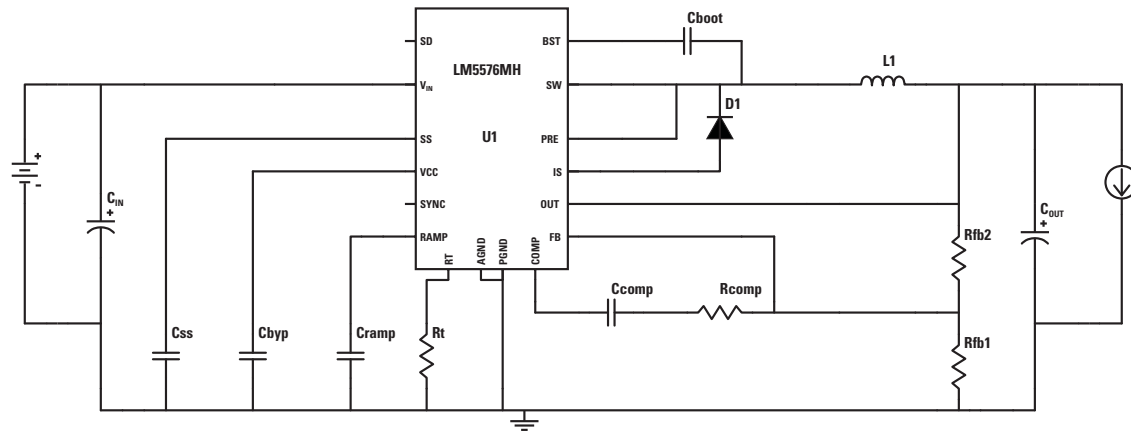
V_{IN}	V_{OUT}	I_{OUT}	C_{FF}	C_{IN}	C_{OUT}	C_{VCC}	L1	R_{FB1}	R_{FB2}	R_{ILIM}	R_{ON}	R_r	C_r	C_{AC}
20 to 42	12	5A	DNS	2.2 μ F, 100V X7R	10 μ F, 16V X7R	2.2 μ F, 10V X7R	10 μ H	10 k Ω	191 k Ω	4.87 k Ω	187 k Ω	4.87 M Ω	180 pF, 50V X7R	560pF, 50V X7R
20 to 42	18	5A	DNS	10 μ F, 63V X7R	22 μ F, 25V X7R	2.2 μ F, 10V X7R	39 μ H	9.76 k Ω	287 k Ω	1.91 k Ω	1.02 M Ω	5.9 M Ω	560 pF, 50V X7R	1.8nF, 50V X7R
36 to 42	24	5A	DNS	4.7 μ F, 100V X7R	10 μ F, 50V X7R	2.2 μ F, 10V X7R	18 μ H	10 k Ω	392 k Ω	2.05 k Ω	487 k Ω	3.16 M Ω	220 pF, 50V X7R	680pF, 50V X7R
36 to 42	30	5A	DNS	2.2 μ F, 100V X7R	10 μ F, 50V X7R	2.2 μ F, 10V X7R	22 μ H	10k Ω	487 k Ω	1.91 k Ω	1.15 M Ω	2.67 M Ω	390 pF, 50V X7R	1.2nF, 100V X7R

LM315x PCB Design



Suggested Further Reading

- AN-1900: LM3150 Evaluation Boards
- AN-1149: Layout Guidelines for Switching Power Supplies
- AN-1229: SIMPLE SWITCHER PCB Layout Guidelines
- Online Seminar: PCB Layout for Switchers



Design Considerations/Performance

- The schematic and PCB layout shown are for the LM5576 but apply to all LM557x devices. For BOM component choice please use the WEBENCH links provided to create the designs.
- For further details refer to the Design Documentation section.

Design Documentation

- Datasheets for: LM5576, LM5575, and LM5574
- AN-1570: LM5576 Evaluation Board
- AN-1569: LM5575 Evaluation Board
- AN-1568: LM5574 Evaluation Board
- Understanding and Applying Current-Mode Control Theory
- Current Mode Modeling – Reference Guide

Component Values (BOM)

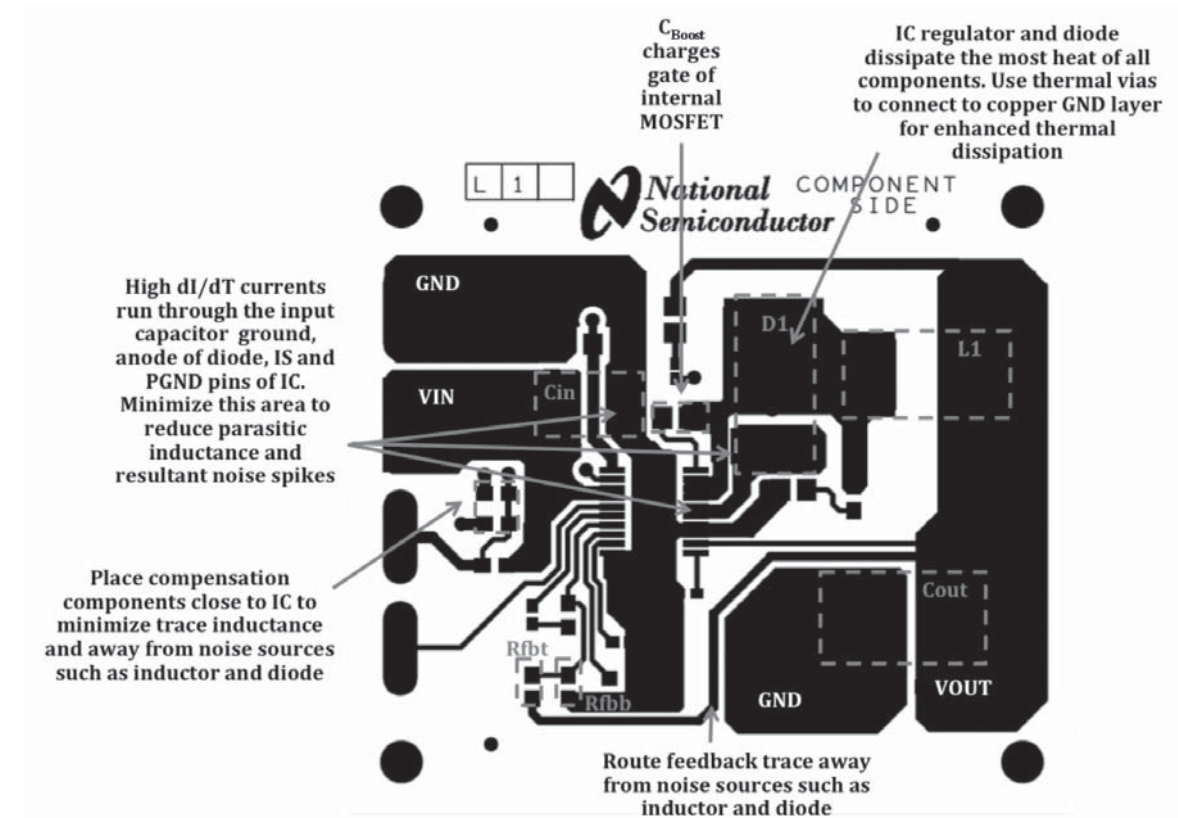
The following table summarizes the values chosen for the designs listed here.

Common Components across all designs

C _{BOOT}	C _{BYP}	C _{SS}	D1
22 nF, X7R, 50V	100 nF, X7R, 25V	10 nF, X7R, 50V	100V, Schottky

Design Specific Components

V _{IN}	V _{OUT}	C _{COMP}	C _{RAMP}	L1	R _{COMP}	C _{COMP2}	C _{IN}	C _{OUT}	C _{RAMP}	R _{FB1}	R _{FB2}	R _T	R _{RAMP}
7V to 75V	1.5V	4.7 nF, X7R, 50V	120 pF, 50V	12 μH	12.44 kΩ	680 pF, X7, 50V	4.7 μF, X7R, 100V	680 μF, 2.5V, Tantalum	120 pF, 50V, COG	1 kΩ	226Ω	24.3 kΩ	Not used
7V to 75V	1.8V	2.2 nF, X7R, 50V	150 pF, 50V	15 μH	23.7 kΩ	560 pF, X7R, 50V	4.7 μF, X7R, 100V	560 μF, 2.5V, AL-Polymer	150 pF, 50V, COG	1 kΩ	475Ω	21.5 kΩ	Not used
7V to 75V	2.5V	2.7 nF, X7R, 50V	150 pF, 50V	15 μH	21.5 kΩ	270 pF, X7R, 50V	1 μF, X7R, 100V	220 μF, 4V, AL-Polymer	150 pF, 50V, COG	1.02 kΩ	1.05 kΩ	20.5 kΩ	Not used
7V to 75V	3.3V	1.8 nF, X7R, 50V	180 pF, 50V	18 μH	28.7 kΩ	150 pF, COG, 50V	2.2 μF, X7R, 100V	180 μF, 6.3V, AL-Polymer	180 pF, 50V, COG	1 kΩ	1.69 kΩ	20.5 kΩ	Not used
7V to 75V	5V	2.2 nF, X7R, 50V	330 pF, 50V	33 μH	34 kΩ	82 pF, COG, 50V	15 μF, X7R, 100V	180 μF, 16V, AL-Polymer	330 pF, 50V, X7R	1 kΩ	3.09 kΩ	34 kΩ	Not used
36V to 75V	12V	1.5 nF, X7R, 50V	470 pF, 50V	47 μH	36.5 kΩ	Not used	1 μF, X7R, 100V	22 μF, 16V, X5R	470 pF, 50V, X7R	1.02 kΩ	8.87 kΩ	20.5 kΩ	Not used
36V to 75V	15V	330 pF, X7R, 50V	560 pF, 50V	56 μH	158 kΩ	150 pF, COG, 50V	1 μF, X7R, 100V	150 μF, 25V, AL-EI	560 pF, 50V, X7R	1 kΩ	11.3 kΩ	20.5 kΩ	Not used
36V to 75V	18V	820 pF, X7R, 50V	680 pF, 50V	68 μH	69.8 kΩ	180 pF, COG, 50V	1 μF, X7R, 100V	27 μF, 25V, AL-EI	680 pF, 50V, X7R	1 kΩ	13.7 kΩ	20.5 kΩ	110 kΩ
36V to 75V	24V	1 nF, X7R, 50V	1 nF, 50V	100 μH	57.6 kΩ	220 pF, COG, 50V	1 μF, X7R, 100V	33 μF, 35V, AL-EI	1 nF, 50V, X7R	1 kΩ	18.7 kΩ	20.5 kΩ	75 kΩ
42V to 75V	30V	470 pF, X7R, 50V	1 nF, 50V	100 μH	124 kΩ	150 pF, COG, 50V	1 μF, X7R, 100V	56 μF, 50V, AL-EI	1 nF, 50V, X7R	1 kΩ	23.7 kΩ	20.5 kΩ	57.6 kΩ



Suggested Further Reading

- AN-1570: LM5576 Evaluation Board
- AN-1569: LM5575 Evaluation Board
- AN-1568: LM5574 Evaluation Board
- RD-128 Reference Design Document
- AN-1566: Techniques for Thermal Analysis of Switching Power Supply Designs
- AN-1229: SIMPLE SWITCHER PCB Layout Guidelines
- AN-1149: Layout Guidelines for Switching Power Supplies
- Online Seminar: PCB Layout for Switchers

LMZ1-Series Power Modules

Product ID	Output Current (A) Max.	Input Voltage (V)	Adjustable Output Voltage (V)	Peak Efficiency (%)	Operating Junction Temperature (°C)	Features	EMI EN55022/CISPR22 Class B Certification		Packaging
							Radiated	Conducted*	
LMZ10503/04/05	3/4/5	2.95 to 5.5	0.8 to 5	96	-40 to 125	EN, SS	✓	✓	TO-PMOD-7
LMZ12001/02/03	1/2/3	4.5 to 20	0.8 to 6	92	-40 to 125	EN, SS	✓	✓	TO-PMOD-7
LMZ14201/02/03	1/2/3	6 to 42	0.8 to 6	90	-40 to 125	EN, SS	✓	✓	TO-PMOD-7
LMZ12008/10	8/10	6 to 20	0.8 to 6	92	-40 to 125	EN, SS	✓	✓	TO-PMOD-11
LMZ13608/10	8/10	6 to 36	0.8 to 6	92	-40 to 125	EN, SS	✓	✓	TO-PMOD-11

NEW

Extended Temperature and High Output Voltage Power Modules

Product ID	Output Current (A) Max.	Input Voltage (V)	Adjustable Output Voltage (V)	Peak Efficiency (%)	Operating Junction Temperature (°C)	Features	EMI EN55022/CISPR22 Class B Certification		Mil Std-883 Testing	Packaging
							Radiated	Conducted*		
LMZ10503/04/05EXT	3/4/5	2.95 to 5.5	0.8 to 5	96	-55 to 125	EN, SS	✓	✓	✓	TO-PMOD-7
LMZ12001/02/03EXT	1/2/3	4.5 to 20	0.8 to 6	92	-55 to 125	EN, SS	✓	✓	✓	TO-PMOD-7
LMZ14201/02/03EXT	1/2/3	6 to 42	0.8 to 6	90	-55 to 125	EN, SS	✓	✓	✓	TO-PMOD-7
LMZ14201H/02H/03H	1/2/3	6 to 42	5 to 24	97	-40 to 125	EN, SS	✓	✓	—	TO-PMOD-7

LMZ2-Series Power Modules

Product ID	Output Current (A) Max.	Input Voltage (V)	Adjustable Output Voltage (V)	Operating Junction Temperature (°C)	Features	EMI EN55022/CISPR22 Class B Certification		Packaging
						Radiated	Conducted*	
LMZ22003/5	3/5	6 to 20	0.8 to 5	-40 to 125	EN, SS, Freq Sync	✓	✓	TO-PMOD-7
LMZ23603/5	3/5	6 to 36	0.8 to 6	-40 to 125	EN, SS, Freq Sync	✓	✓	TO-PMOD-7
LMZ22008/10	8/10	6 to 20	0.8 to 6	-40 to 125	EN, SS, Freq Sync, Current Share	✓	✓	TO-PMOD-11
LMZ23608/10	8/10	6 to 36	0.8 to 6	-40 to 125	EN, SS, Freq Sync, Current Share	✓	✓	TO-PMOD-11

NEW

*Additional input filter required

Non-Synchronous Regulators

Product ID	Output Current (A)	Input Voltage (V)	Adjustable Output Voltage (V)	Frequency Range (kHz)	Adj.	On/Off Pin	PWM Mode	Packaging
LM22671/74	0.5	4.5 to 42	1.285 to 37	200 to 1000 Adj	✓/—	✓	Voltage	PSOP-8
LM22672/75	1	4.5 to 42	1.285 to 37	200 to 1000 Adj	✓/—	✓	Voltage	PSOP-8
LM22680	2	4.5 to 42	1.285 to 37	200 to 1000 Adj	✓	✓	Voltage	PSOP-8
LM22670/73/76	3	4.5 to 42	1.285 to 37	200 to 1000 Adj	✓/—/—	—/✓/✓	Voltage	TO263-7 Thin, PSOP-8
LM22677/78/79	5	4.5 to 42	1.285 to 37	200 to 1000 Adj	✓/—/—	✓/✓/—	Voltage	TO263-7 Thin
LM25574	0.5	6 to 42	1.23 to 40	50 to 1000, Sync	✓	✓	Current	TSSOP-16
LM25575	1.5	6 to 42	1.23 to 40	50 to 1000, Sync	✓	✓	Current	eTSSOP-16
LM25576	3	6 to 42	1.23 to 40	50 to 1000, Sync	✓	✓	Current	eTSSOP-20
LM5574	0.5	6 to 75	1.23 to 70	50, Sync	✓	✓	Current	TSSOP-16
LM5575	1.5	6 to 75	1.23 to 70	50, Sync	✓	✓	Current	eTSSOP-16
LM5576	3	6 to 75	1.23 to 70	50, Sync	✓	✓	Current	eTSSOP-20

Synchronous Regulators

Product ID	Output Current (A)	Input Voltage (V)	Adjustable Output Voltage (V)	Frequency Range (kHz)	Sync	PWM Mode	Packaging
LM3103	0.75	4.5 to 42	0.6 to 38	up to 1000 Adj	—	COT	eTSSOP-16
LM3100	1.5	4.5 to 36	0.8 to 32	up to 1000 Adj	—	COT	eTSSOP-20
LM3102	2.5	4.5 to 42	0.8 to 38	up to 1000 Adj	—	COT	eTSSOP-20
LM2852	2	2.85 to 5.5	0.8 to 3.3	500, 1500	—	Voltage Mode	eTSSOP-14
LM2853	3	3 to 5.5	0.8 to 3.3	550	—	Voltage Mode	eTSSOP-14
LM2854	4	2.95 to 5.5	0.8 to 5	500, 1000	—	Voltage Mode	eTSSOP-16

Synchronous Controllers

Product ID	Input Voltage (V)	Output Min (V)	Output Max (V)	Feedback Tolerance (%)	Frequency Range (kHz) and Sync	Packaging
LM3150	6 to 42	0.6	Adj	1.50	up to 1000 Adj	eTSSOP-14
LM3151	6 to 42	3.3	3.3	1.50	250	eTSSOP-14
LM3152	6 to 33	3.3	3.3	1.50	500	eTSSOP-14
LM3153	6 to 18	3.3	3.3	1.50	750	eTSSOP-14



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated